

IWIPP 2027 – Kitakyushu, Fukuoka, Japan February 28-March 4

International Workshop on Integrated Power Packaging 2027

Your opportunity to share with and learn from the experts in the Power Packaging & System Design world. Though packaging is in our name, we're about a lot more than that - we want to talk about system design / control, testing & reliability, dielectrics, materials, manufacturing, and more.

Information / Call for Papers

Abstract Deadline Extended: October 23, 2026 (Fri)

Since the first IWIPP in 1998, the workshop has focused on advanced power packaging and integration technologies that maximize the performance of power semiconductor devices. With the rapid expansion of AI data centers and electric vehicles, these technologies have become more important than ever. IWIPP 2027 will bring together researchers and engineers from around the world to discuss the latest developments in the field.



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History of IWIPP

1st IWIPP 1998

September 17-19, 1998, The Congress Plaza Hotel, Chicago, IL, USA

General Chair: Krishna Shenai, University of Illinois at Chicago, USA

Technical Program Chair: Douglas C. Hopkins, The State University of New York at Buffalo, USA

2nd IWIPP 2000

July 14-15, 2000, Westin Hotel, Waltham, MA, USA

General Chair: Douglas C. Hopkins, The State University of New York at Buffalo, USA

Technical Program Chair: Guo-Quan Lu, CPES, Virginia Tech, USA

3rd IWIPP 2015

May 3-6, 2015, The Congress Plaza Hotel Chicago, IL, USA

General Chair: Krishna Shenai, LoPel Corporation, USA

Technical Program Chair: Ty McNutt, Arkansas Power Electronics International, USA

4th IWIPP 2017

April 5-7, 2017, Aula Conference Center, TU-Delft, Netherlands

General Chair: Ty McNutt, Wolfspeed, USA

Technical Program Chair: Patrick McCluskey, University of Maryland, USA

5th IWIPP 2019

April 24-26, 2019, ENSEEIHT, Toulouse, France

General Chair: Thierry Lebey, CNRS, University of Toulouse, France

Technical Program Chair: Brandon Passmore, Wolfspeed, USA

6th IWIPP 2022

August 24-26, 2022, Centre de congrès, Grenoble, France

General Chair: Francesco Iannuzzo, AAU Energy, Aalborg University, Denmark

Technical Program Chair: Nicholas (Nick) Baker, The University of Alabama, USA

7th IWIPP 2025

April 8-10, 2025, Hotel Capstone, Tuscaloosa, AL, USA

General Chair: Andy Lemmon, The University of Alabama, USA

Technical Program Co-Chairs: Nicholas (Nick) Baker, Arthur Boutry, The University of Alabama, USA



City of
Kitakyushu

Supported by IEEE PELS Japan Joint
Chapter and IEEE PELS Fukuoka Chapter

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IWIPP TECHNICAL SCOPE

Device and Application

- Power Semiconductor Devices
- Die attach and wire bonding
- Packaging Materials
- High Temperature & High Voltage Dielectrics
- Interconnection technologies
- Printed Circuit Boards (PCB)
- High-Frequency Magnetics
- Thermal Interface Materials
- Electromagnetic Interference

Integration and Design

- Design for Manufacturability, Compatibility with Standards Innovative packaging strategies
- High-Temperature Capacitors
- System Integration and Optimization
- Compact Converter Design Techniques
- Gate/Base Drivers, Sensors & Protection

Reliability and Test

- Components to System Reliability
- Reliability Assessment & Lifetime Prediction
- Partial Discharge
- Thermal Management
- Power Cycling
- Environmental test
- Failure analysis

IMPORTANT DATES

- ◆ **October 23, 2026: 2-page abstract deadline extended.**
- ◆ November 26, 2026: Notification of acceptance.
- ◆ January 18, 2027, Final four-page manuscript submission and copyright deadline.
- ◆ Final manuscript will be published in IEEE Xplore after the workshop.

<http://iwipp.org/paper-submission/>



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International Workshop on Integrated Power Packaging 2027

Keynote Speakers



Prof. Johann W. Kolar
*ETH Zurich, Switzerland /
TU Wien, Austria*



Prof. Victor Veliadis
*North Carolina State
University, USA*

Invited Speakers



Dr. Peter Friedrichs
*Infineon Technologies,
Germany*



Dr. Jürgen Leib
*Fraunhofer IISB,
Germany*



Dr. Ivana Kovacevic
*ETH Zurich,
Switzerland*



Dr. Jacek Rudzki
*Semikron Danfoss GmbH,
Germany*

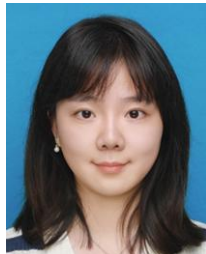
Tutorial Speakers



Prof. Nando Kaminski
*University of Bremen,
Germany*



Prof. Thomas Ebel
*University of Southern
Denmark, Denmark*



Prof. Weijia Zhang
*Hong Kong University of
Science and Technology,
Hong Kong*



Prof. Yoshikazu Takahashi
Tohoku University, Japan



Dr. Lars Boettcher
*Fraunhofer IZM,
Germany*



International Workshop on Integrated Power Packaging 2027

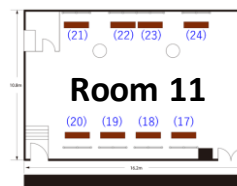
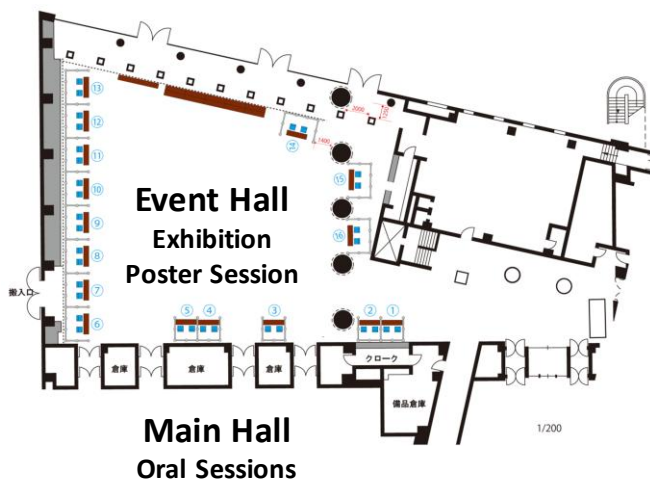
Preliminary Schedule

	Sunday Feb. 28	Monday Mar. 1	Tuesday Mar. 2	Wednesday Mar. 3	Thursday Mar. 4
AM	Conference Room Tutorial 1 Prof. Nando Kaminski	Main Hall Opening Keynote Prof. Johann Kolar	Main Hall Invited talk Dr. Jürgen Leib	Main Hall Invited talk Dr. Jacek Rudzki	Lab tour (TBD)
	Tutorial 2 Dr. Thomas Ebel	Oral Session 1	Oral Session 4	Oral Session 7	
Lunch	Conference Room Tutorial 3 Prof. Weijia Zhang	Main Hall Invited talk Dr. Peter Friedrichs	Main Hall Invited talk Prof. Ivana Kovacevic	Main Hall Keynote Prof. Victor Veliadis	
PM	Tutorial 4 Prof. Yoshikazu Takahashi	Oral Session 2	Oral Session 6	Oral Session 9	
	Tutorial 5 Dr. Lars Böttcher	Oral Session 3	Event Hall Poster Session	Closing	
Social Events	Event Hall Welcome Reception	Exhibition site Event Hall / Room 11 Exhibition open Mar. 1 AM to Mar. 3 AM	Hotel New Tagawa (TBD) Banquet	 IWIPP 2027 Kitakyushu International Conference Center 3-9-30 Asano, Kokurakita-ku, Kitakyushu, Fukuoka 802-0001, Japan	

Exhibition

Exhibition Site: Event Hall / Room 11

Open from the morning of March 1 to the morning of March 3



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IWIPP 2027 Committee

Steering Committee

Prof. Andrew Lemmon	University of Alabama
Prof. Francesco Iannuzzo	Politecnico di Torino
Dr. Ty McNutt	Wolfspeed
Dr. Brian Narveson	PSMA
Dr. Thierry Lebey	Safran Tech

Organizing Committee

General Chair	Prof. Ichiro Omura	Kyushu Institute of Technology
General Co-Chair	Ms. Shiori Idaka	Mitsubishi Electric Europe
Technical Co-Chair	Prof. Hiroshi Kono	Kyushu Institute of Technology
Technical Co-Chair	Dr. Naoto Fujishima	Fuji Electric Co. Ltd., Japan
Publicity Chair	Dr. Hodaka Rokubuichi	Mitsubishi Electric
Publications Chair	Dr. Tomohide Terashima	Kyushu University
Partnership Chair	Dr. Fumiyoshi Kawashiro	Toshiba Electronic Devices & Storage Corp., Japan
Treasurer	Dr. Masahiro Tanaka	Synopsys

Technical Program Committee

Prof. Thomas Baslar	TU Chemnitz, Germany
Prof. Aylin Bicakci	Kiel University of Applied Sciences, Germany
Dr. Cyril Buttay	INSA Lyon, France
Dr. Nicolas Dagrenne	Mitsubishi Electric R&D Centre Europe, France
Dr. Sombel Diahm	LAPLACE Research Institute, University of Toulouse, France
Dr. Eckart Hoene	Fraunhofer IZM, Germany
Dr. Fumiyoshi Kawashiro	Toshiba Electronic Devices & Storage Corp., Japan
Dr. Munaf Rahimo	mqSemi AG, Switzerland
Dr. David Reusch	Texas Instruments, USA
Prof. Wataru Saito	Kyushu University, Japan
Dr. Uwe Schilling	Semikron Danfoss, Germany
Dr. Zhao Shuaijie	Fuji Electric Co., Ltd., Japan
Prof. Keiji Wada	Tokyo Metropolitan University, Japan
Prof. Huai Wang	Aalborg University, Denmark
Dr. Olaf Wittler	Fraunhofer IZM, Germany
Dr. Kan Yasui	MinebeaMitsumi Inc., Japan
Dr. Guang Zeng	Greenel Semiconductor Co., Ltd., China



International Workshop on Integrated Power Packaging 2027

Registration Fee

Workshop(Mar. 1-4)	Early registration until Jan. 20, 2027 (JST)	Registration after Jan.21, 2027 (JST)
Member of IEEE	100,000	110,000
Non-member	110,000	120,000
Student Member of IEEE	55,000	65,000
Student non-member	65,000	70,000

Student fee does not include Banquet ticket.
Banquet ticket can be purchased at the registration.

Tutorial(Feb. 28)	Early registration until Jan. 20, 2027 (JST)	Registration after Jan.21, 2027 (JST)
Member of IEEE	60,000	65,000
Non-member	65,000	70,000
Student Member of IEEE	45,000	50,000
Student non-member	50,000	55,000

Student registration is for a full-time student at the time of conference.

Visa Information

Nationals of certain countries may be required to obtain a visa to enter Japan. Please check whether you need a visa by visiting the following website:
https://www.mofa.go.jp/j_info/visit/visa/short/novisa.html
 You may also obtain information from the Japanese Embassy or Consulate-General in your country or region. If you need further assistance, please contact the IWIPP 2027 Secretariat. Visa support desk will be open, soon.



International Workshop on Integrated Power Packaging 2027

Conference Venue

Kitakyushu International Conference Center

3-9-30 Asano, Kokurakita-ku, Kitakyushu, Fukuoka 802-0001, Japan



Hotels

Rihga Royal Hotel Kokura

2-14-2 Asano, Kokurakita-ku, Kitakyushu,
Fukuoka 802-0001, Japan

JR Kyushu Station Hotel Kokura

1-1-1 Asano, Kokurakita-ku, Kitakyushu,
Fukuoka 802-0001, Japan

Daiwa Roynet Hotel KOKURA-EKIMAE

1-5-14 Uomachi, Kokurakita-ku, Kitakyushu,
Fukuoka 802-0006 Japan

ART HOTEL Kokura New Tagawa

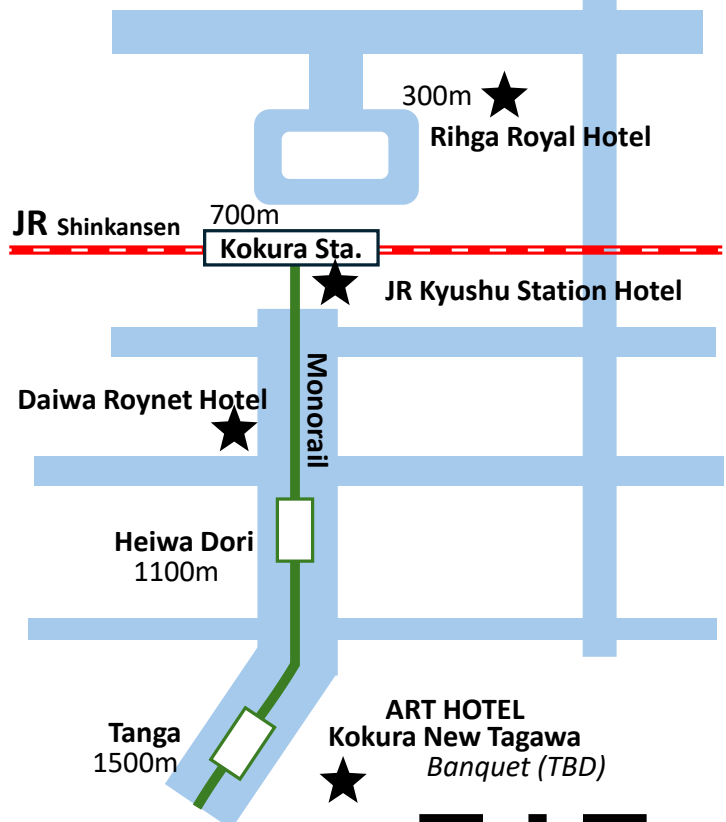
3-46 Furusemba-machi, Kokurakita-ku,
Kitakyushu, Fukuoka 802-0082 Japan

◆ **Many affordable and clean hotels
near JR Kokura station**

◆ **Monorail: every 10 min / ¥100**



**IWIPP 2027
Conference Venue**



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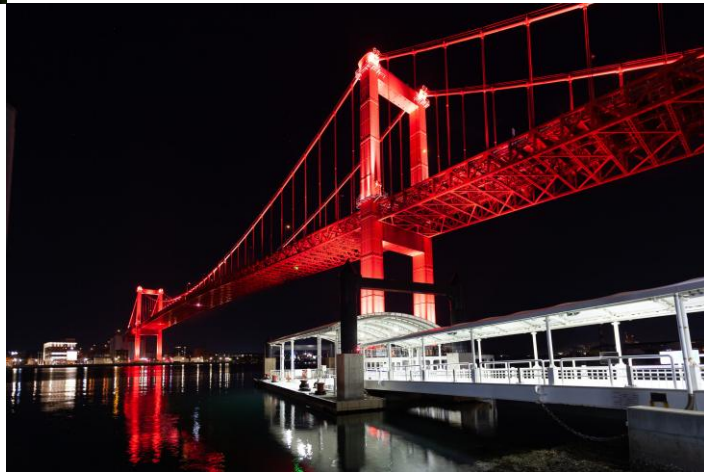


Kokura Castle

Kokura Castle was built in 1602 by Hosokawa Tadaoki, a famous samurai lord, shortly after the Battle of Sekigahara, which marked the beginning of the Edo period. In 1959, the castle tower was restored at the request of the citizens of Kitakyushu.

Wakato Bridge

Completed in 1962, the Wakamato Bridge spans Dokai Bay and connects the Wakamatsu and Tobata districts of Kitakyushu. When it opened, it was the longest suspension bridge in Asia. Visitors can also enjoy a ride on the shuttle boats that operate beneath the bridge.



Dokai Bay Industry Aria

After Japan's first modern steelworks began operation in Yahata in 1901, the Dokai Bay area developed into a major center of heavy industry and chemical manufacturing. Following a period of severe air and water pollution, the combined efforts of local citizens and industry successfully restored the environment, bringing back blue skies and clean seawater.

Kanmon Strait Bridge

The Kanmon Bridge is a famous suspension bridge spanning the Kanmon Strait. Completed in 1973, the 1,068-meter-long bridge was the longest suspension bridge in Asia at the time of its construction. The Kanmon Strait is a 27.7-kilometer-long waterway that separates Honshu, Japan's main island, from Kyushu. Known for its ever-changing currents, the strait experiences tidal flows of up to 9.4 knots (17.4 km/h). Visitors can also cross the strait on foot through the Kanmon Pedestrian Tunnel.

